

Industry-Academic Forum on EMC 2023

“Early-Career Scientist and Researchers”

Poster Pitches and Presentations (Day 1, 16:00 – 18:00)



Test Design Methodology for Immunity Investigations Using Electric Near-Field Probes

Assistant Prof. Xinglong Wu
Politecnico di Milano, Milan, Italy



Robust Bayesian Optimization for Electronic Devices Design

Jixiang Qing
IDLab, Department of Information Technology, Ghent University – imec, Belgium



S-parameter Modeling and Optimization using Deep Gaussian Processes

Federico Garbuglia
IDLab, Department of Information Technology, Ghent University – imec, Belgium



Bio Electromagnetic Compatibility of Brain Implants

Hamideh Esmaeili
Institut für Theoretische Elektrotechnik - Hamburg University of Technology (TUHH),
Germany



Using the Orbital Angular Momentum (OAM) Mode System on Multiconductor Transmission Lines

Michael Wulff
Institut für Theoretische Elektrotechnik - Hamburg University of Technology (TUHH),
Germany

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Physics Based Full Design Space Exploration of Realistic PCB Power Delivery Networks

Youcef Hassab

Institut für Theoretische Elektrotechnik - Hamburg University of Technology (TUHH), Germany



Validation of Physics Based Via Modeling For High Speed Communication On PCBs

Til Hillebrecht

Institut für Theoretische Elektrotechnik - Hamburg University of Technology (TUHH), Germany



Bridging The Gap Between Artificial Neural Networks and Kernel Regressions in EM Applications

Nastaran Soleimani

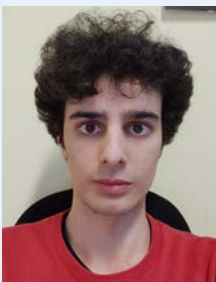
Politecnico di Torino, Torino, Italy



Enabling Fast System-Level Simulation and Optimization Via Parameterized Macromodeling

Tommaso Bradde

Politecnico di Torino, Torino, Italy



Towards Accelerated Transient Solvers For Power Integrity Verification

Antonio Carlucci

Politecnico di Torino, Torino, Italy

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EMC Risk Analysis : Novel Approach via Efficient Training of Surrogate Model

Alexandre Plot
Thales SIX France and IETR, France



Measurements of High-Speed Interconnects in Automotive-Grade PCBs

Jose Enrique Hernandez Bonilla
Bosch, Germany and Institut für Theoretische Elektrotechnik – Hamburg University
of Technology (TUHH), Germany